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Harnden et al.

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(54) **PORTION OF A MATRIX FOR SURFACE MOUNT PACKAGE LEADFRAME**

(75) Inventors: **James Harnden**, Hollister, CA (US); **Richard K. Williams**, Cupertino, CA (US); **Anthony Chia**, Singapore (SG); **Chu Weibing**, Shanghai (CN); **Allen K. Lam**, Fremont, CA (US)

(73) Assignee: **GEM Services, Inc.**, San Jose, CA (US)

(**) Term: **14 Years**

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(51) **LOC (7) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Search** D13/182; 29/622, 29/704, 827; 174/52.2, 52.4; 206/713, 714, 715, 716, 727, 728; 257/667, 668; 333/185; 428/573

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Primary Examiner—Philip S. Hyder
Assistant Examiner—Selina Sikder
(74) *Attorney, Agent, or Firm*—Townsend and Townsend and Crew LLP

(57) **CLAIM**

The ornamental design for a portion of a matrix for surface mount package leadframe, as shown and described.

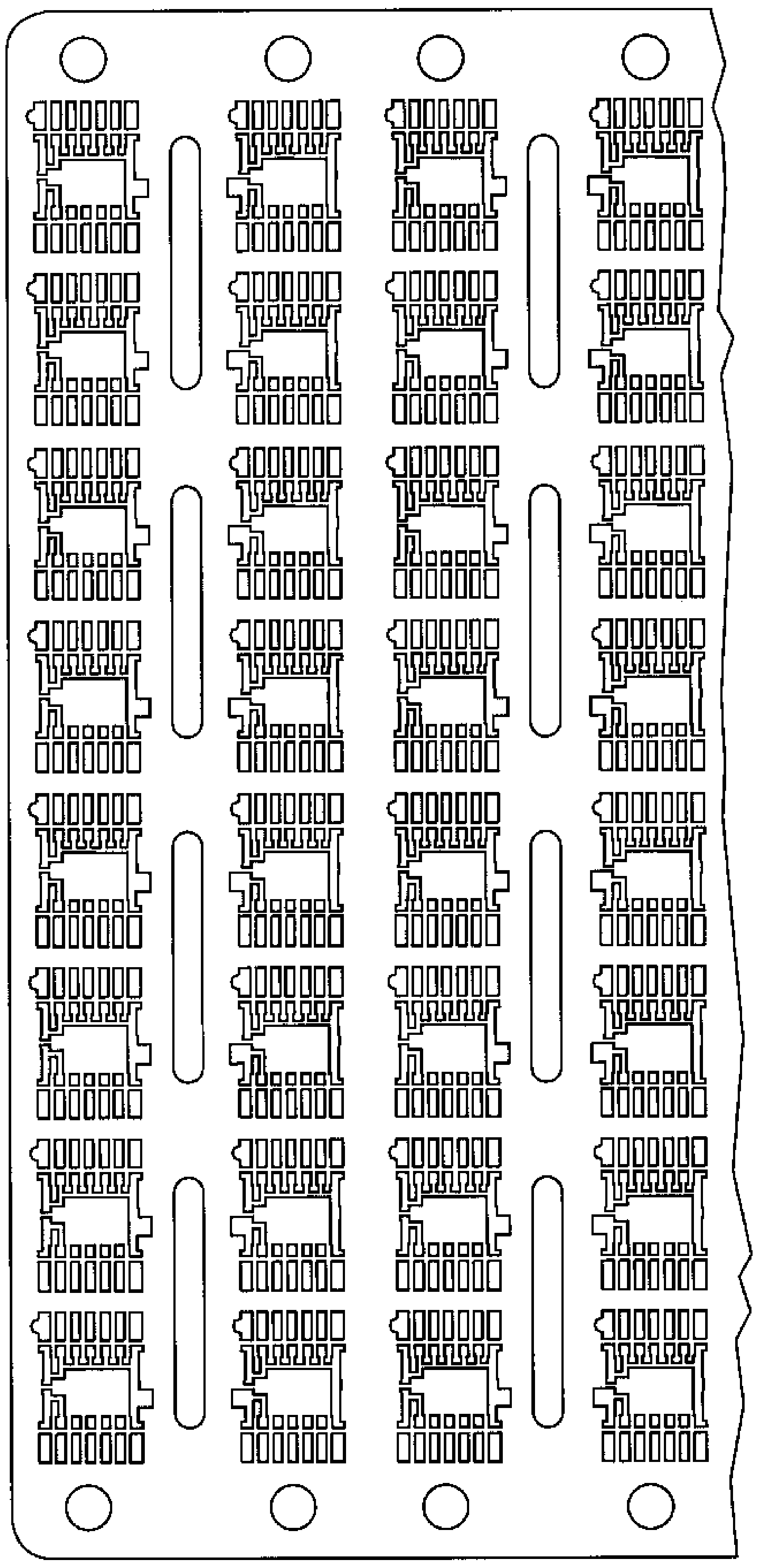
DESCRIPTION

FIG. **1** is a top plan view of a portion of a matrix for surface mount package leadframe showing my new design;

FIG. **2** is a top plan view of an enlarged fragment of the portion of a matrix for surface mount package leadframe; and,

FIG. **3** is a perspective view of a portion of a matrix for surface mount package leadframe.

1 Claim, 3 Drawing Sheets



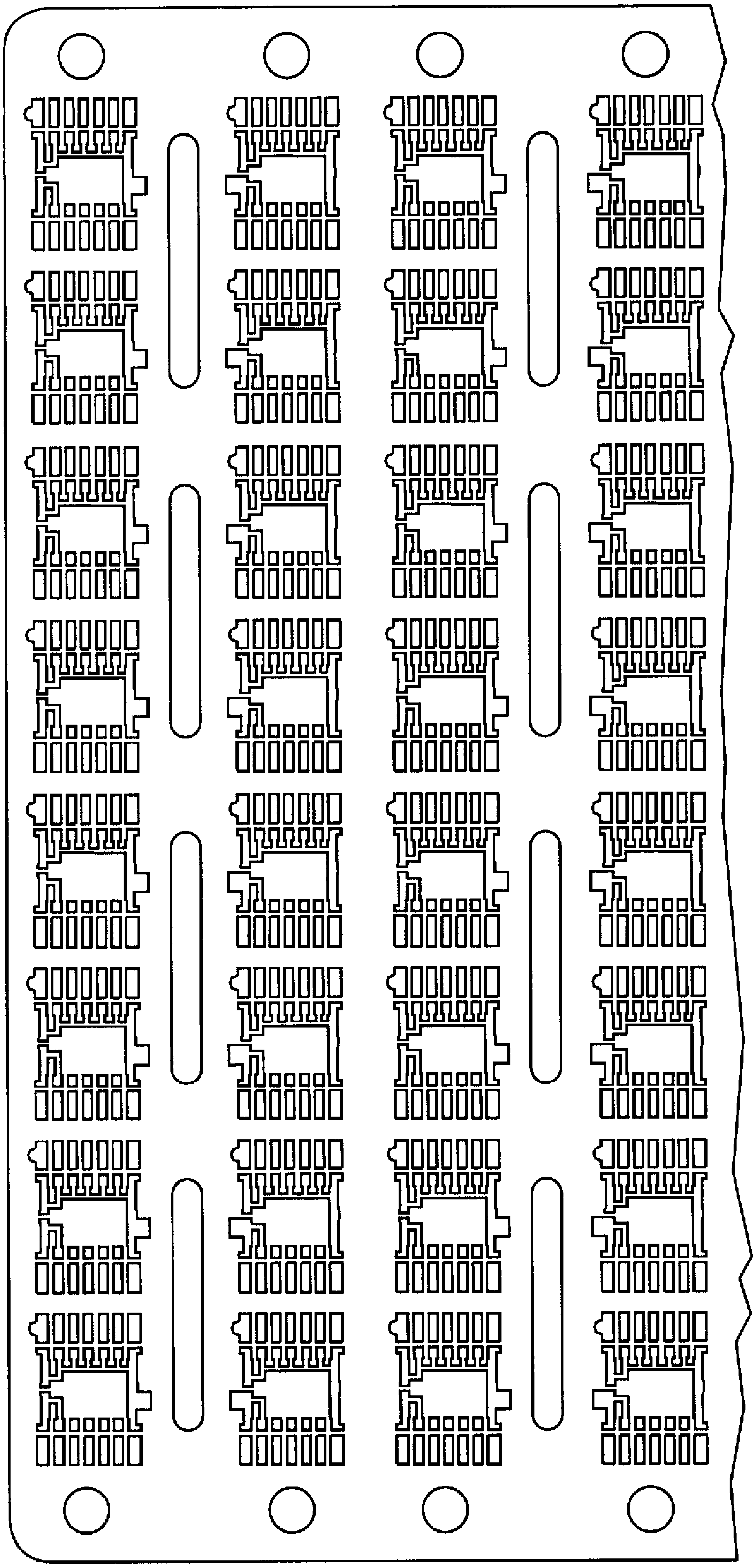


FIG. 1

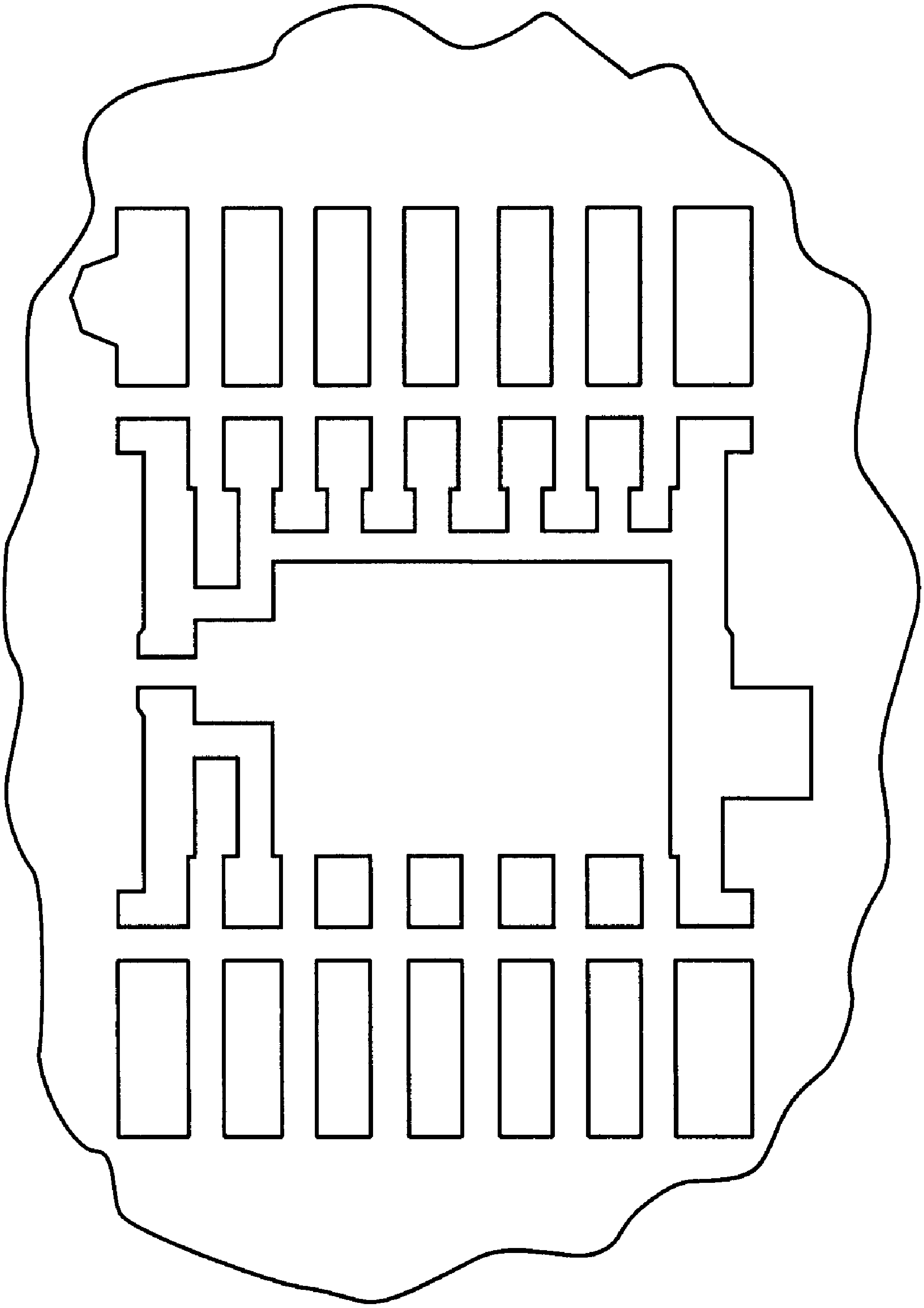


FIG. 2

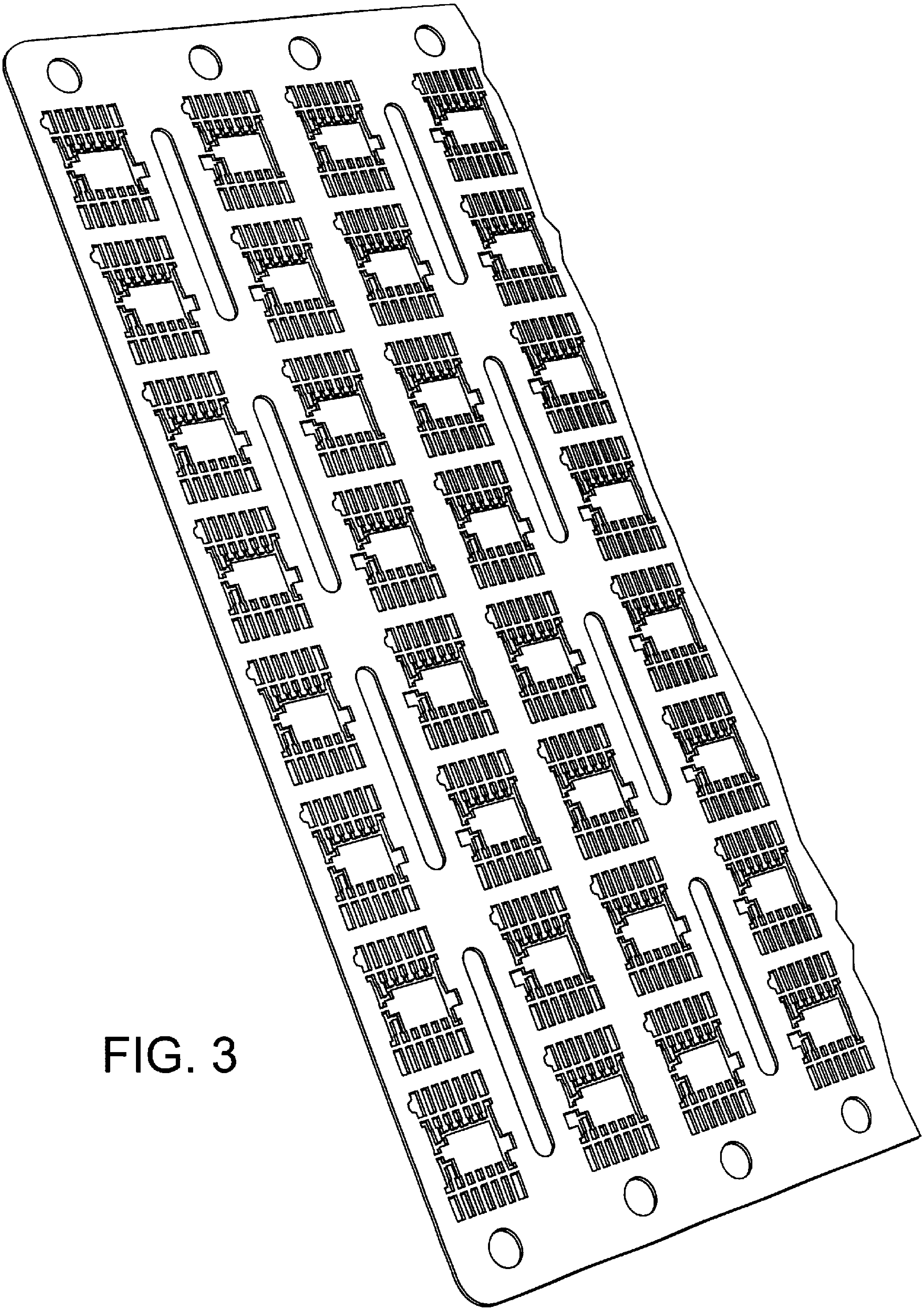


FIG. 3